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10046858

Title of Invention:

Method and apparatus for

placing circuit modules

First Named Inventor:

Steven Teig

Domestic/Foreign Application:

Domestic Application

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TRANSMITTAL

Electronic Version v1.1 Stylesheet Version v1.1.0

Title of Invention

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Application Number:

10/046858

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

Method and apparatus for placing circuit modules

Application Number:

10/046858

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6767

First Named Applicant:

Steven Teig

Attorney Docket Number: SPLX.P0124

Art Unit:

2825

Examiner:

LEIGH M. GARBOWSKI

Search string:

(4777606 or 5224057 or 5519836 or 5699265 or 6018623 or 6038385 or 6085032 or 6088519

or 6154874 or 6240541 or 6349403 or 6366279 or 6442745 or 6505331 or 6601227 or

20030014725 or 20040044979).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4777606	1988-10-11	Fournier			
	2	5224057	1993-06-29 Igarashi et al.				
	3	5519836	1996-05-21	Gawlick et al.			
	4	5699265	1997-12-16	Scepanovic et al.			
	5	6018623	2000-01-25	Chang et al.			
	6	6038385	2000-03-14	Scepanovic et al.			
	7	6085032	2000-07-04	Scepanovic et al.			
	8	6088519	2000-07-11	Koford			
	9	6154874	2000-11-28	Takahashi			
	10	6240541	2001-05-29	Yasuda et al.			
	11	6349403	2002-02-19	Dutta et al.			
	12	6366279	2002-04-02	Gorman et al.	B1		
	13	6442745	2002-08-27	08-27 Arunachalam et al.			
	14	6505331	2003-01-07	Bracha et al.	B1		
	15	6601227	2003-07-21	Trimberger	B1		

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030014725	2003-01-16	Sato et al.	A1		
	2	20040044979	2004-03-04	Aji et al.	· A1		

Signature

Examiner Name	Date